

FEATURES AND SPECIFICATIONS



0.75mm (.030") Pitch AMC.0 B+ 170-Circuit Connectors

[查询"75908-0001"供应商](#)

75800 Standard
75908 Pegless
75791 Extended Height



Series 75800 Standard AMC.0 B+ Connector

AMC.0 B+ connectors from Molex support the next generation of mezzanine card standards and 12.5 Gbps speeds

The 170-circuit AMC.0 B+, or AdvancedMC™ connectors from Molex support the next generation of mezzanine card standards that allow for hot-plugging of high-speed serial interconnects. These connectors support AdvancedTCA (Advanced Telecommunications Computing Architecture), a standard developed by PICMG (PCI Industrial Computer Manufacturers Group).

Molex AMC.0 B+ connectors feature controlled impedance and reduced crosstalk, plus a footprint launch optimized for high-speed data rates. This design enables the connector to achieve 12.5 Gbps NRZ (Non Return to Zero) signal transmission. This enhanced

footprint further reduces crosstalk by managing inter-pair affinity and incorporating additional ground vias for isolation. As a result, the AMC.0 B+ connectors achieve crosstalk of less than 3 percent at 12.5 Gbps.

Three versions of the Molex AMC.0 B+ connector exist: the standard connector with locating pegs (series 75800), connector without pegs (series 75908) and the 1.15mm (.045") extended-height connector (series 75791). This taller height is optimized for blade-server applications where cooling is critical.

Features and Benefits

- Insert-molded wafer design provides excellent electrical performance
- Press-fit contacts and high-speed footprint for simpler application to PCB and superior signal integrity than competition
- Tin or Tin-Lead tail plating supports RoHS requirements and customer preferences for press-fit
- Meets PICMG Advanced MC™ specification and industry standard requirements

SPECIFICATIONS

Reference Information

Packaging: Tray
UL File No.: E29179
CSA File No.: LR19980
Mates With: AMC module
Designed In: Millimeters

Electrical

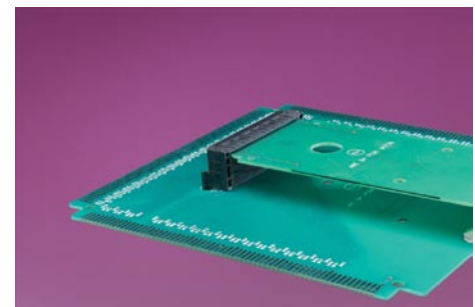
Voltage: 250V AC
Current: 1.5A Power Terminal
1.0A Other Terminals
Contact Resistance: 60 milliohms max.
Dielectric Withstanding Voltage: 80V RMS
Insulation Resistance: 500V DC

Mechanical

Insertion Force to PCB: 6050N (1360 lbf) max.
Mating Force: 100N (22 lbf) max.
Unmating Force: 65N (14 lbf) max.
Durability: 200 cycles

Physical

Housing: Black Thermoplastic
Contact: Copper (Cu) Alloy
Plating:
Contact Area — 0.76µm Gold (Au)
Solder Tail Area — Tin or Tin-Lead (Sn or Sn/Pb)
Underplating — Nickel (Ni)
PCB Thickness: 2.36mm (.092")
Operating Temperature: -40 to +105°C



APPLICATIONS

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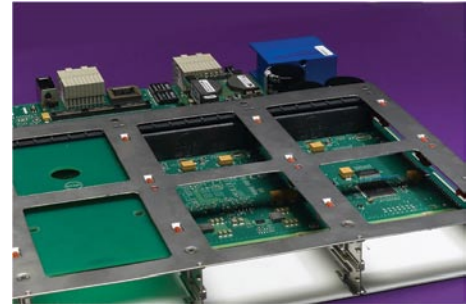
- Telecommunications equipment
- For use in the IEEE 1386 market as it transitions to serial buses
- General "blade" computing applications
- Extended-height version used in non-ATCA applications
- Any hot-pluggable high-speed serial bus application



ATCA Rack



ATCA Carrier



ORDERING INFORMATION

Order No.	Comment	Tail Plating	Height	PCB Peg
75800-0001	With alignment pegs	Tin plated	21.85mm (.860")	Yes
75800-0002	With alignment pegs	Tin/Lead plated	21.85mm (.860")	Yes
75908-0001	Without alignment pegs	Tin plated	21.85mm (.860")	No
75908-0002	Without alignment pegs	Tin/Lead plated	21.85mm (.860")	No
75791-0001	Extended height	Tin plated	23.0mm (.905")	Yes
75791-0002	Extended height	Tin/Lead plated	23.0mm (.905")	Yes

Americas Headquarters
Lisle, Illinois 60532 U.S.A.
1-800-78MOLEX
amerinfo@molex.com

Asia Pacific North Headquarters
Yamato, Kanagawa, Japan
81-462-65-2324
feninfo@molex.com

Asia Pacific South Headquarters
Jurong, Singapore
65-6268-6868
fesinfo@molex.com
Visit our website at www.molex.com

European Headquarters
Munich, Germany
49-89-413092-0
eurinfo@molex.com

Corporate Headquarters
2222 Wellington Ct.
Lisle, IL 60532 U.S.A.
630-969-4550
Fax: 630-969-1352